


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST25TV512-AP6G3	CBA3*TVIP0UC	A	994I	2018-12-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	0.26	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Not Applicable	N/A		

Package Designator	Size	Nbr of instances	Shape	
CHP	0.954x0.853x0.120	4	No lead	
Comment	Package : A3 GOLD BUMPED DICE DM00249510			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	CBA3*TVIPOUC				2000000.0	996104.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.247	mg	supplier	die	Silicon (Si)	7440-21-3		0.227	mg	919028	888802
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	8097	7831
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	4049	3915
Bump	M-011 Other inorganic materials	0.007	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.017	mg	68826	66562
				supplier	Bump metalization	Gold (Au)	7440-57-5		0.007	mg	1000000	28994